Asynchronous Clear

TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
′164	36 MHz	21 mW per bit
'LS164	36 MHz	10 mW per bit

#### description

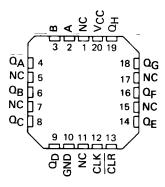
These 8-bit shift registers feature gated serial inputs and an asynchronous clear. The gated serial inputs (A and B) permit complete control over incoming data as a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock pulse. A high-level input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is high or low, but only information meeting the setup-time requirements will be entered. Clocking occurs on the low-to-high-level transition of the clock input. All inputs are diode-clamped to minimize transmission-line effects.

The SN54164 and SN54LS164 are characterized for operation over the full military temperature range of  $-55\,^{\circ}$ C to 125 $\,^{\circ}$ C. The SN74164 and SN74LS164 are characterized for operation from 0 $\,^{\circ}$ C to 70 $\,^{\circ}$ C.

SN54164, SN54LS164...J OR W PACKAGE SN74164...N PACKAGE SN74LS164...D OR N PACKAGE (TOP VIEW)

<b>д</b> [	1 2	14 V <sub>CC</sub>
$a_A \Box$	3	12 \( \oldsymbol{12} \)
$\alpha_{B}$ [	4	11 QF
α <sub>C</sub> □	5	10∏ <b>Q</b> E
$\sigma_{D} \sqsubset$	6	9 ☐ CLR
GND [	7	8DCLK

# SN54LS164 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

### **FUNCTION TABLE**

L	INPUTS			OUTPUTS					
CLEAR	CLOCK	Α	В	$\alpha_{A}$	$\alpha_{B}$	Q <sub>H</sub>			
L	X	Х	Х	L	L	L			
Н	L	×	Х	Q <sub>A0</sub>	$o_{B0}$	$\alpha_{H0}$			
Н	1	н	Н	Н	$\mathbf{Q}_{An}$	$Q_{Gn}$			
Н	1	L	X	L	$\mathbf{Q}_{An}$	$q_{Gn}$			
Н	1	Х	L	L	Q <sub>An</sub>	$Q_{Gn}$			

H = high level (steady state), L = low level (steady state)

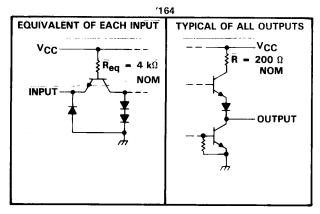
X = irrelevant (any input, including transitions)

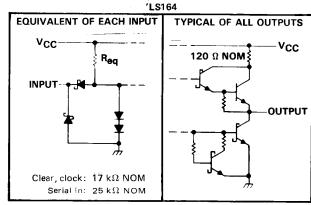
↑ = transition from low to high level.

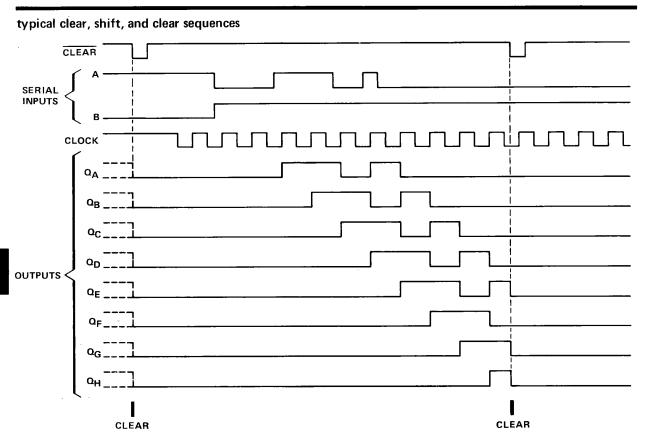
 ${
m Q}_{A0},\,{
m Q}_{B0},\,{
m Q}_{H0}$  = the level of  ${
m Q}_A,\,{
m Q}_B,\,{
m or}\,\,{
m Q}_H,$  respectively, before the indicated steady-state input conditions were established.

Q<sub>An</sub>, Q<sub>Gn</sub> = the level of Q<sub>A</sub> or Q<sub>G</sub> before the most-recent ↑ transition of the clock; indicates a one-bit shift.

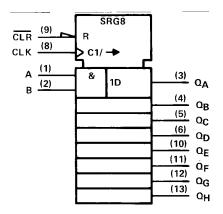
#### schematics of inputs and outputs





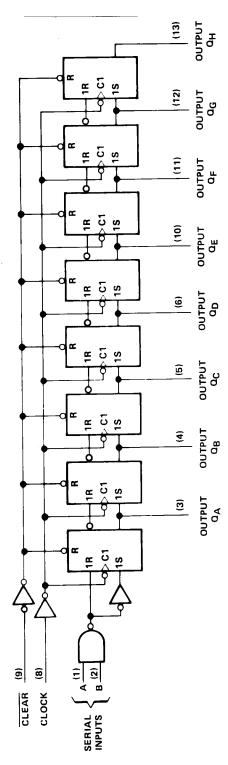


logic symbol†



 $<sup>^{\</sup>dagger}$ This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

## logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

## SN54164, SN74164 **8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS**

absolute maximum ratings over oprating	g free-air temperature range (unless otherwise noted)
Input voltage	

NOTE 1: Voltage values are with respect to network ground terminal.

## recommended operating conditions

		SN5416	4	SN74164		UNIT	
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, VCC	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-400			-400	μΑ
Low-level output current, IQL			8	<u> </u>		8	mA
Clock frequency, fclock	0		25	0		25	MHz
Width of clock or clear input pulse, tw	20			20			ns
Data setup time, t <sub>su</sub> (see Figure 1)	15			15			ns
Data setup time, t <sub>SU</sub> (Clear Inactive) (see Figure 1)	20			20			ns
Data hold time, th (see Figure 1)	5			5	<del>-</del>		ns
Operating free-air temperature, TA	- 55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	•	SN54164			SN74164			UNIT
PARAMETER	TEST CONDITIONS	MIN	ТҮР‡	MAX	MIN	TYP‡	MAX	UNII
VIH High-level input voltage		2			2			٧
VIL Low-level input voltage				8.0			0.8	\ \
VIK Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = -12 mA			-1.5			-1.5	V
VOH High-level output voltage	$V_{CC} = MIN$ , $V_{IH} = 2 V$ , $V_{IL} = 0.8 V$ , $I_{OH} = -400 \mu A$	2.4	3.2		2.4	3.2		٧
VOL Low-level output voltage	$V_{CC} = MIN, V_{IH} = 2 V,$ $V_{IL} = 0.8 V, I_{OL} = 8 mA$		0.2	0.4		0.2	0.4	V
I Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V,			1			1	mA
IIH High-level input current	V <sub>CC</sub> = MAX, V <sub>1</sub> = 2.4 V			40			40	μA
IL Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-1.6			-1.6	mA
IOS Short-circuit output current §	V <sub>CC</sub> = MAX	-10		-27.5	-9		-27.5	mA
	V <sub>CC</sub> = MAX, V <sub>I(clock)</sub> = 0.4 V	Î	30			30		mA
ICC Supply current	See Note 2 V <sub>I(clock)</sub> = 2.4 V		37	54		37	54	]

<sup>†</sup> For conditions shown at MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICC is measured with outputs open, serial inputs grounded, and a momentary ground, then 4.5 V, applied to clear.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ} \text{ C}$

	PARAMETER	TEST CONDIT	MIN	TYP	MAX	UNIT	
f <sub>max</sub>	Maximum clock frequency		C <sub>L</sub> = 15 pF	25	36		MHz
	Propagation delay time, high-to-low-level	i	C <sub>L</sub> = 15 pF		24	36	ns
<sup>t</sup> PHL	Q outputs from clear input	B 800 G	C <sub>L</sub> = 50 pF		28	42	1
	Propagation delay time, low-to-high-level	R <sub>L</sub> = 800 Ω,	C <sub>L.</sub> = 15 pF	8	17	27	ns
+	Q outputs from clock input	See Figure 1	C <sub>L</sub> = 50 pF	10	20	30	] ""
	Propagation delay time, high-to-low-level		C <sub>L</sub> = 15 pF	10	21	32	ns
tPHL			C <sub>L</sub> = 50 pF	10	25	37	]



<sup>‡</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25°C.

<sup>§</sup> Not more than two outputs should be shorted at a time.

## SN54LS164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

absolute maximum ratings over operati	tings over operating free-air temperature range (unless otherwise noted)  CC (see Note 1)				
	7 V 7 V 9e: SN54LS164 -55°C to 125°C SN74LS164 -0°C to 70°C -65°C to 150°C				
Storage temperature range					
NOTE 1: Voltage values are with respect to network	k ground terminal.				

#### recommended operating conditions

		S	N54LS1	64	S	N74LS1	64	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	٧
ЮН	High-level output current			- 0.4			- 0.4	mΑ
lOL	Low-level output current			4			8	mA
fclock	Clock frequency	0		25	0		25	MHz
tw	Width of clock or clear input pulse	20			20			ns
t <sub>su</sub>	Data setup time (See Figure 1)	15			15			ns
t <sub>su</sub>	Clear inactive setup time (See Figure 1)	20			20		_	ns
th	Data hold time (See Figure 1)	5			5			ns
TA	Operating free-air temperature	- 55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244552	TEST CONDITIONS!	S	N54LS1	64	S	UNIT			
PARAMETER	TEST CONDITIONS†	MIN	TYP <sup>‡</sup>	MAX	MIN	TYP <sup>‡</sup>	MAX	UNII	
VIK	$V_{CC} = MIN$ , $I_I = -18 \text{ mA}$	·			- 1.5			<b>- 1</b> .5	٧
V <sub>OH</sub>	$V_{CC} = MIN$ , $V_{IH} = 2 V$ , $V_{II}$ $I_{OH} = -0.4 \text{ mA}$	L = MAX,	2.5	3.5		2.7	3.5		٧
	$V_{CC} = MIN$ , $V_{IH} = 2 V$ ,	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	V
$v_{OL}$	V <sub>IL</sub> = MAX	I <sub>OL</sub> = 8 mA					0.35	0.5	]
l <sub>l</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V			·	0.1			0.1	mA
ін	$V_{CC} = MAX$ , $V_I = 2.7 V$			20			20		μΑ
ΙΙL	$V_{CC} = MAX$ , $V_I = 0.4 V$				-0.4			-0.4	mA
los	V <sub>CC</sub> = MAX		- 20		- 100	- 20		- 100	mA
lcc	V <sub>CC</sub> = MAX, See Note 3	_		16	27		16	27	mA

<sup>†</sup>For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, VCC = 5 V, TA = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency		25	36		MHz
tPHL	Propagation delay time, high-to-low-level Q outputs from clear input	$R_L = 2 k\Omega$ , $C_L = 15 pF$ ,		24	36	ns
tPLH	Propagation delay time, low-to-high-level Q outputs from clock input	See Figure 1		17	27	ns
tPHL	Propagation delay time, high-to-low-level Q outputs from clock input			21	32	ns



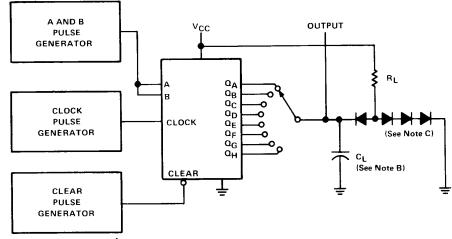
 $<sup>^{\</sup>ddagger}$ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.

<sup>&</sup>lt;sup>5</sup>Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

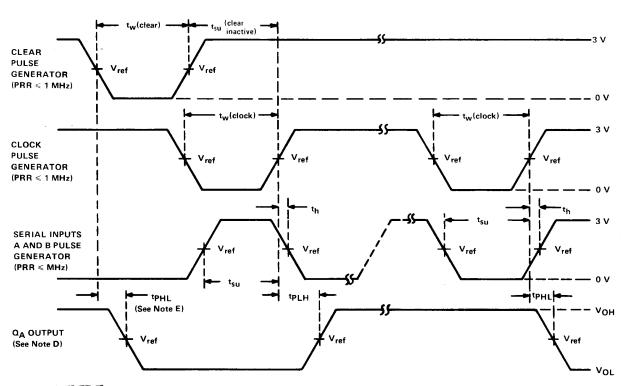
NOTE 3: I<sub>CC</sub> is measured with outputs open, serial inputs grounded, the clock input at 2.4 V, and a momentary ground, then 4.5 V applied to clear.

## SN54164, SN54LS164, SN74164, SN74LS164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

## PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



#### **VOLTAGE WAVEFORMS**

- NOTES: A. The pulse generators have the following characteristics: duty cycle  $\leq$  50%,  $Z_{out} \approx$  50  $\Omega$ ; for '164,  $t_r \leq$  10 ns,  $t_f \leq$  10 ns, and for LS164,  $t_r \leq$  15 ns,  $t_f \leq$  6 ns.
  - B. C<sub>L</sub> includes probe and jig capacitance.
  - C. All diodes are 1N3064 or equivalent.
  - D. QA output is illustrated. Relationship of serial input A and B data to other Q outputs is illustrated in the typical shift sequence.
  - E. Outputs are set to the high level prior to the measurement of tpHL from the clear input.
  - F. For '164,  $V_{ref} = 1.5 \text{ V}$ ; for 'LS164,  $V_{ref} = 1.3 \text{ V}$ .

FIGURE 1-SWITCHING TIMES



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## **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/30605B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605B2A	Samples
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
JM38510/30605BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Samples
JM38510/30605BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
JM38510/30605BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Samples
JM38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples
JM38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Sample
JM38510/30605SDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Sample
JM38510/30605SDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Sample
M38510/30605B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605B2A	Sample
M38510/30605B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605B2A	Sample
M38510/30605BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Sample
M38510/30605BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BCA	Sample
M38510/30605BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Sample
M38510/30605BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605BDA	Sample
M38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Sample





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
M38510/30605SCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SCA	Samples
M38510/30605SDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
M38510/30605SDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30605SDA	Samples
SN54LS164J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS164J	Samples
SN54LS164J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS164J	Samples
SN74LS164D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164	Samples
SN74LS164D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164	Samples
SN74LS164DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164	Samples
SN74LS164DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164	Samples
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164	Samples
SN74LS164DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS164	Samples
SN74LS164N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Samples
SN74LS164N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Samples
SN74LS164NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Samples
SN74LS164NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS164N	Samples
SN74LS164NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Samples
SN74LS164NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Samples
SN74LS164NSRE4	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Samples
SN74LS164NSRE4	ACTIVE	so	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS164	Samples
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 164FK	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS164FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 164FK	Samples
SNJ54LS164J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164J	Samples
SNJ54LS164J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164J	Samples
SNJ54LS164W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164W	Samples
SNJ54LS164W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS164W	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

## **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN54LS164, SN54LS164-SP, SN74LS164:

Catalog: SN74LS164, SN54LS164

Military: SN54LS164

Space: SN54LS164-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

**PACKAGE MATERIALS INFORMATION** 

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## TAPE AND REEL INFORMATION





A0	<u> </u>
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
I	SN74LS164DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
I	SN74LS164NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS164DR	SOIC	D	14	2500	853.0	449.0	35.0
SN74LS164NSR	SO	NS	14	2000	853.0	449.0	35.0

## **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



\*All dimensions are nominal

iii dililerisions are nomina								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/30605B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/30605B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74LS164D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS164N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164NE4	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS164NE4	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54LS164FK	FK	LCCC	20	1	506.98	12.06	2030	NA

## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## W (R-GDFP-F14)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



## D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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